LINEAR TECHNOLOGY MATERIALS DECLARATION

lt1189cn8#pbf **(Engineering Calculation)** **PDIP**

(printed on: 2020-07-11 18:06:16) **TOTAL MASS (g): 0.498311**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.001817**	**1000000**	**3646.31518555**
Die Coat	Dow Corning	Silicone	69430-27-9	**0.000435**	**1000000**	**872.948303223**
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.149760	975000	300535.03125
		Iron (Fe)	7439-89-6	0.003686	24000	7396.98242188
		Phosphorus (P)	7723-14-0	0.000046	300	92.3117752075
		Zinc (Zn)	7440-66-6	0.000108	700	216.732009888
		Nickel (Ni)	7440-02-0	0.000000	0	0
		Silicon (Si)	7440-21-3	0.000000	0	0
		Magnesium (Mg)	7439-95-4	0.000000	0	0
		Tin (Sn)	7440-31-5	0.000000	0	0
		Lead Frame Total:		**0.153600**	**1000000**	**308241.0625**
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
		Exter. Plating Sn	7440-31-5	0.012410	1000000	24904.6953125
		External Plating Total:		**0.012410**	**1000000**	**24904.6953125**
		Inter. Plating Ni	7440-02-0	0.000000	0	0
		Inter. Plating Ag	7440-22-4	0.001228	1000000	2464.32299805
		Internal Plating Total:		**0.001228**	**1000000**	**2464.32299805**
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000644	750000	1292.36486816
		Tin (Sn)	7440-31-5	0.000000	0	0
		Lead (Pb)	7439-92-1	0.000000	0	0
		Silica (SiO2)	60676-86-0	0.000000	0	0
		Indium (In)	7440-74-6	0.000000	0	0
		Metal Oxide		0.000000	0	0
		Antimony (Sb)	7440-36-0	0.000000	0	0
		Resin (EP)		0.000215	250000	431.457214355
		Die Attach Total:		**0.000859**	**1000000**	**1723.82214355**
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.078670	240000	157873.21875
		Bromine (Br)	40039-93-8	0.003278	10000	6578.21777344
		Silica (SiO2)	60676-86-0	0.236011	720000	473621.625
		Antimony Trioxide (Sb2O3)	1309-64-4	0.009834	30000	19734.6523438
		Metal Hydroxide		0.000000	0	0
		Carbon Black (C)	1333-86-4	0.000000	0	0
		Encapsulation Total:		**0.327793**	**1000000**	**657807.6875**
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**0.000169**	**1000000**	**339.145446777**
					TOTAL MASS (g):	**0.498311**